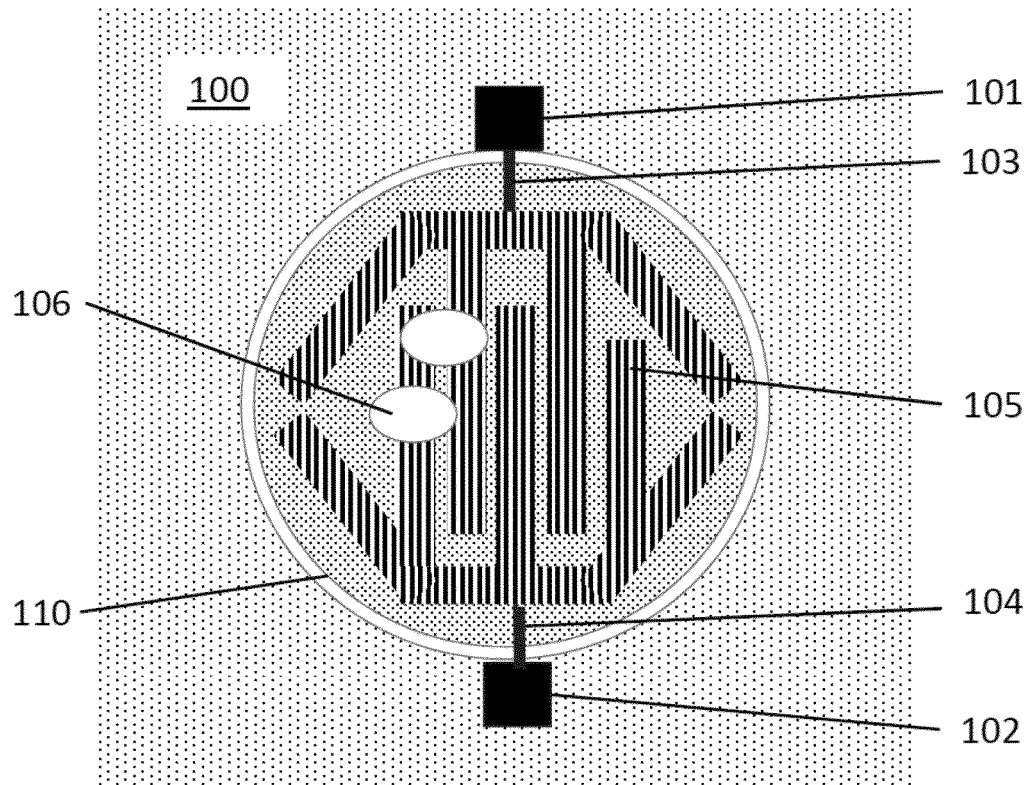
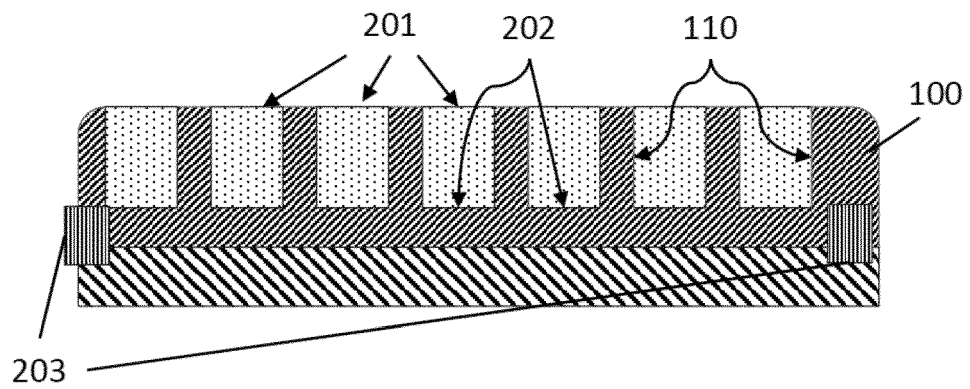
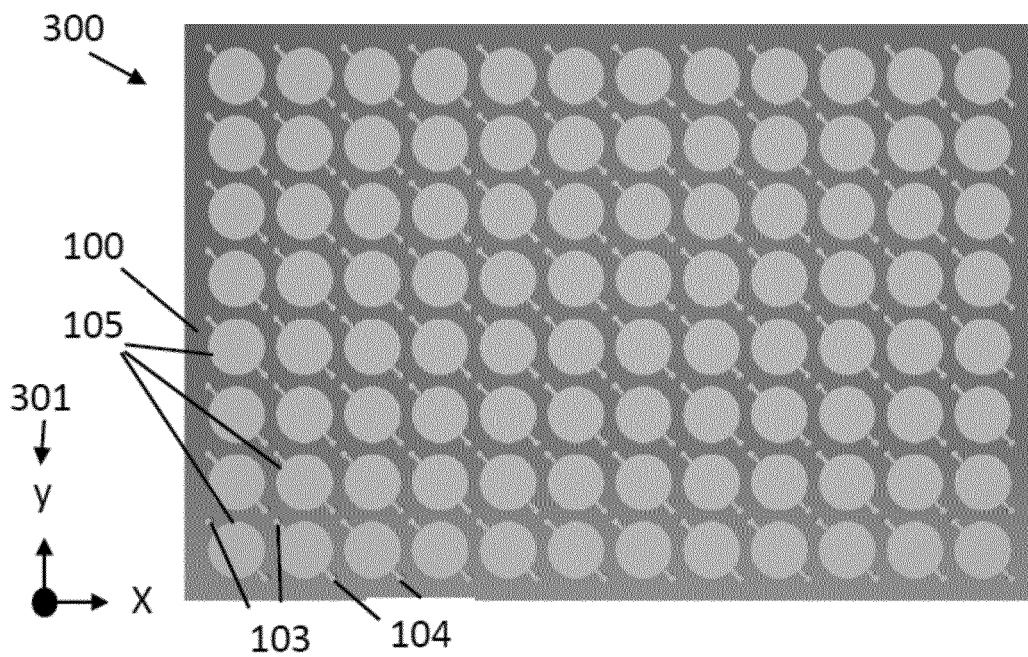
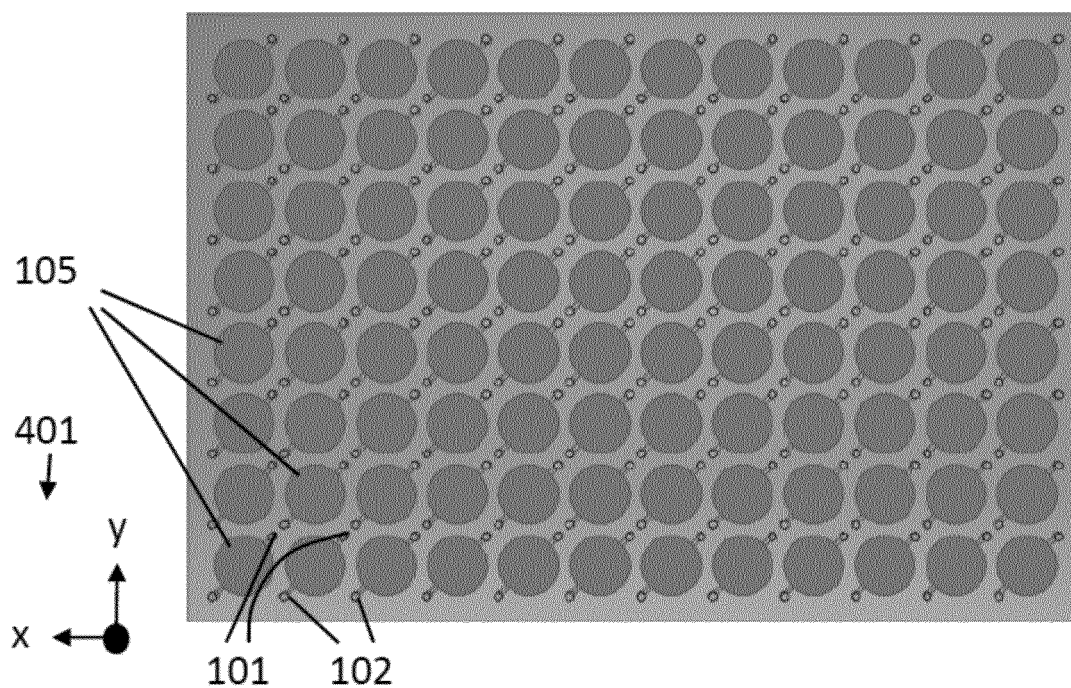
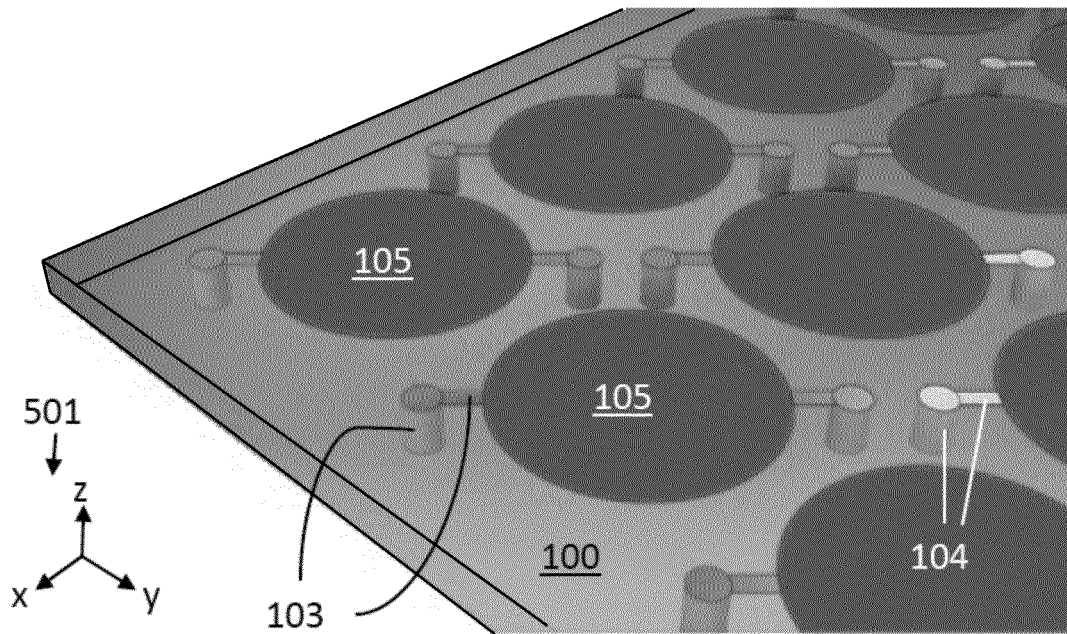
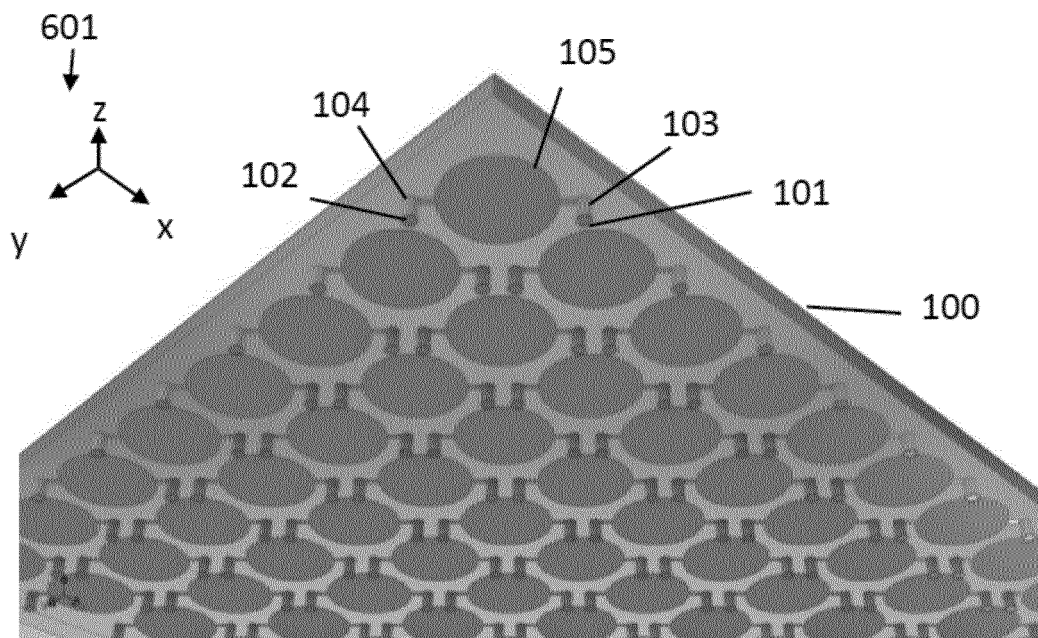


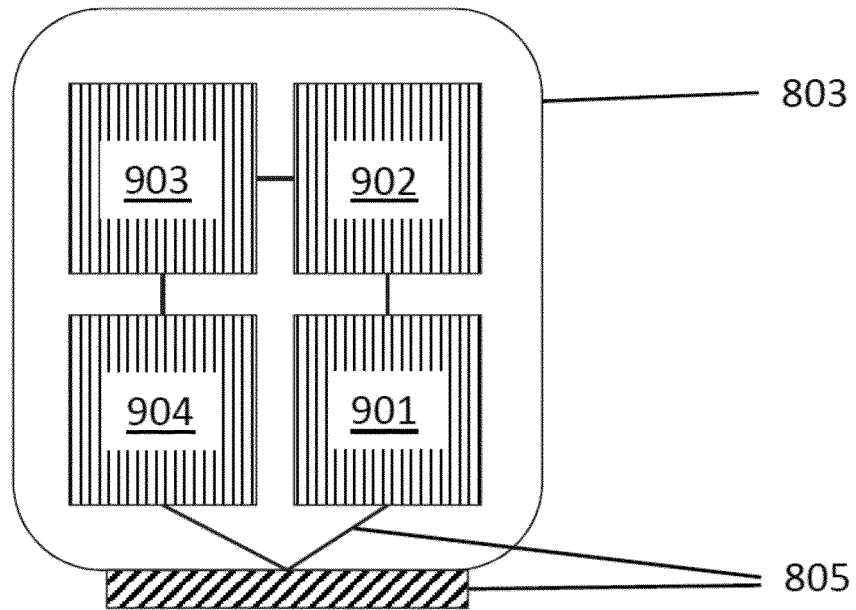
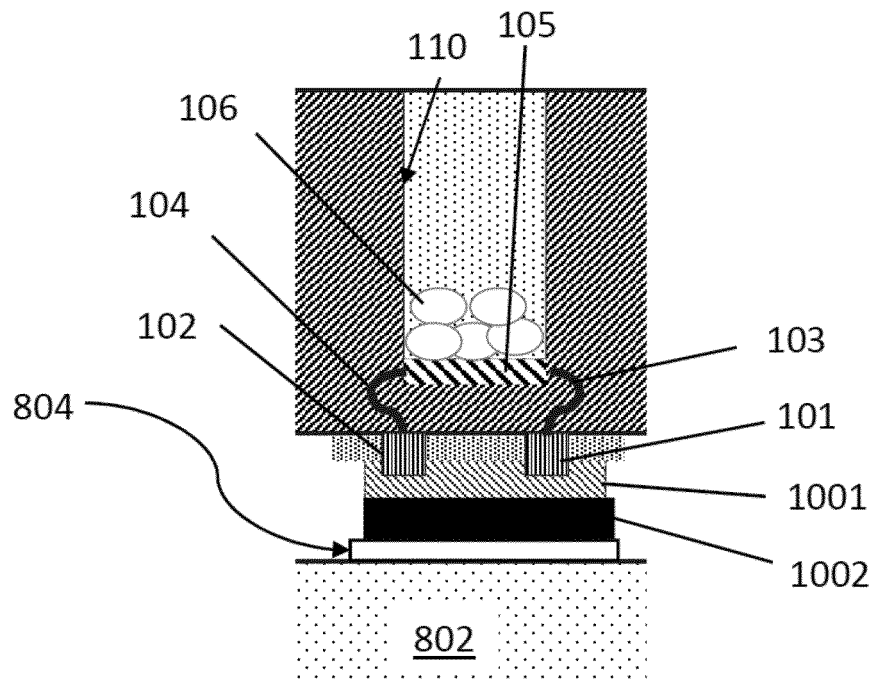
**FIG. 1****FIG. 2**

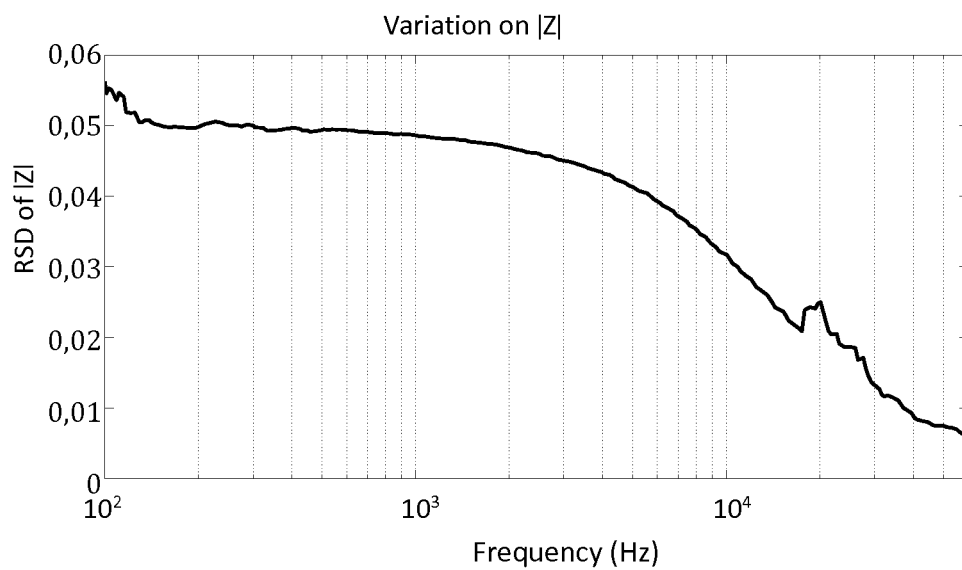
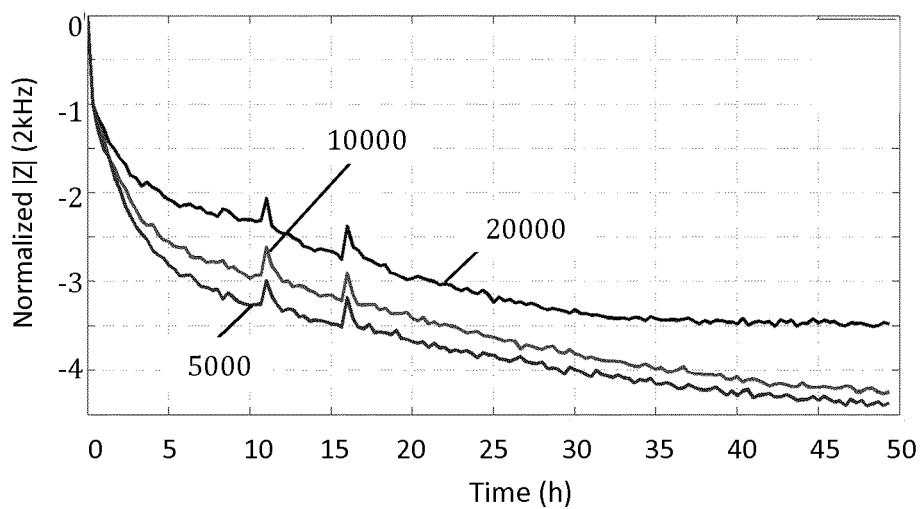
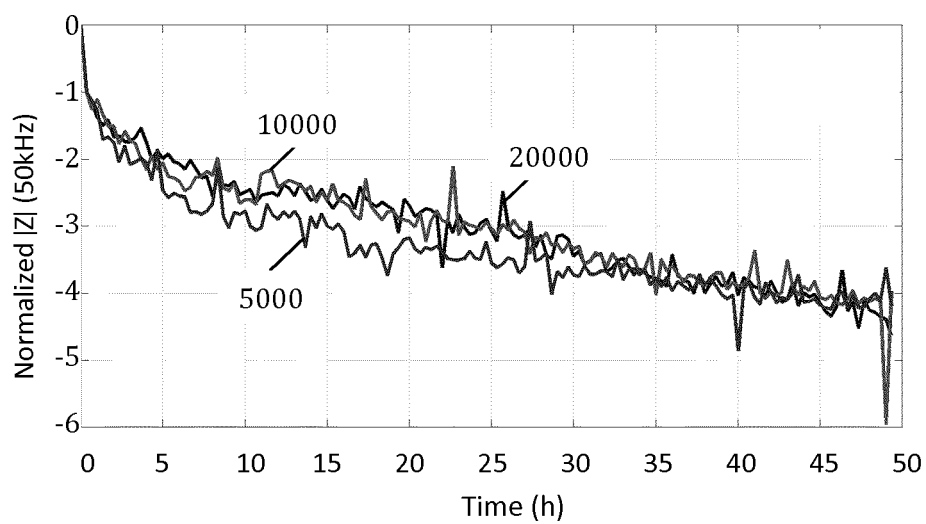
**FIG. 3****FIG. 4**

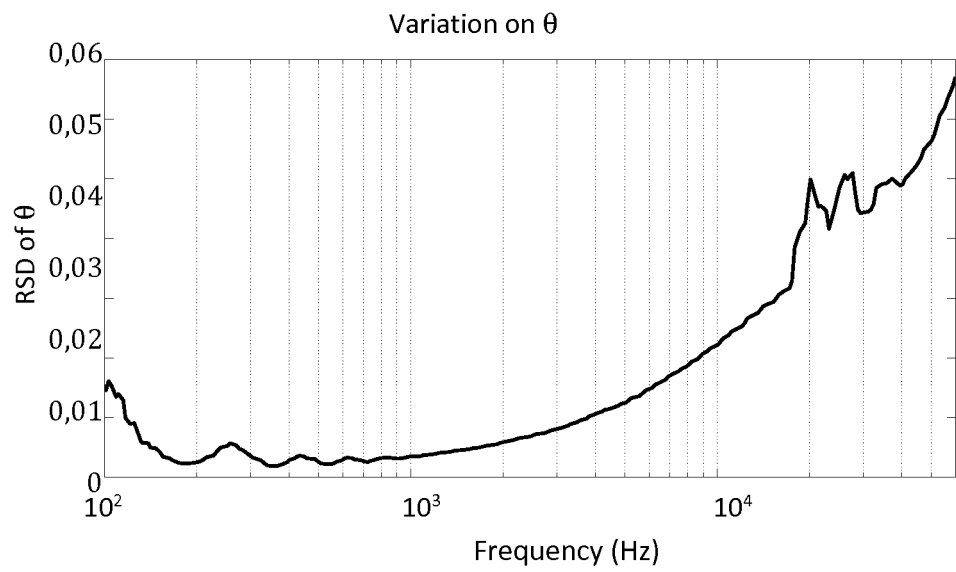
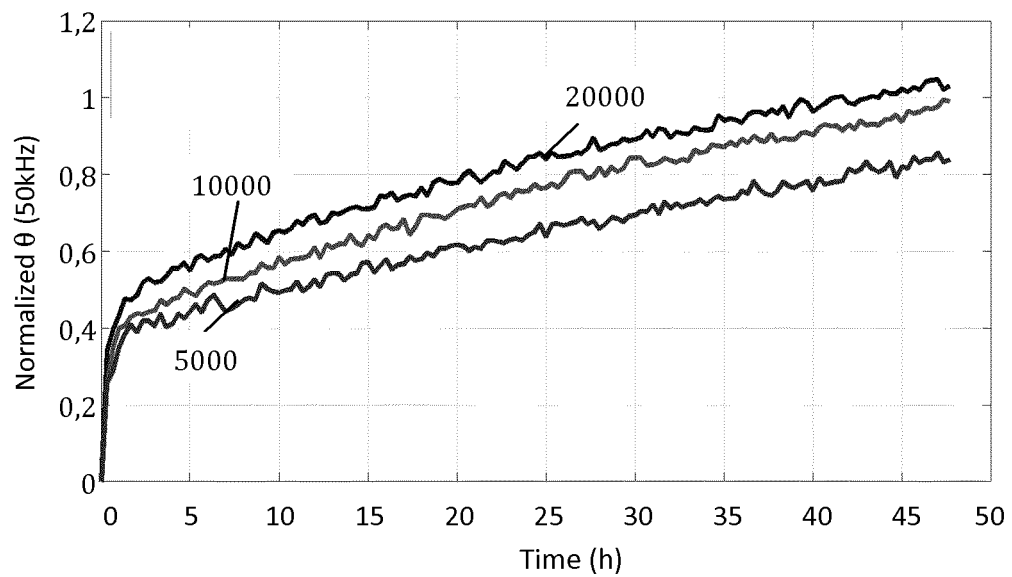
**FIG. 5****FIG. 6**

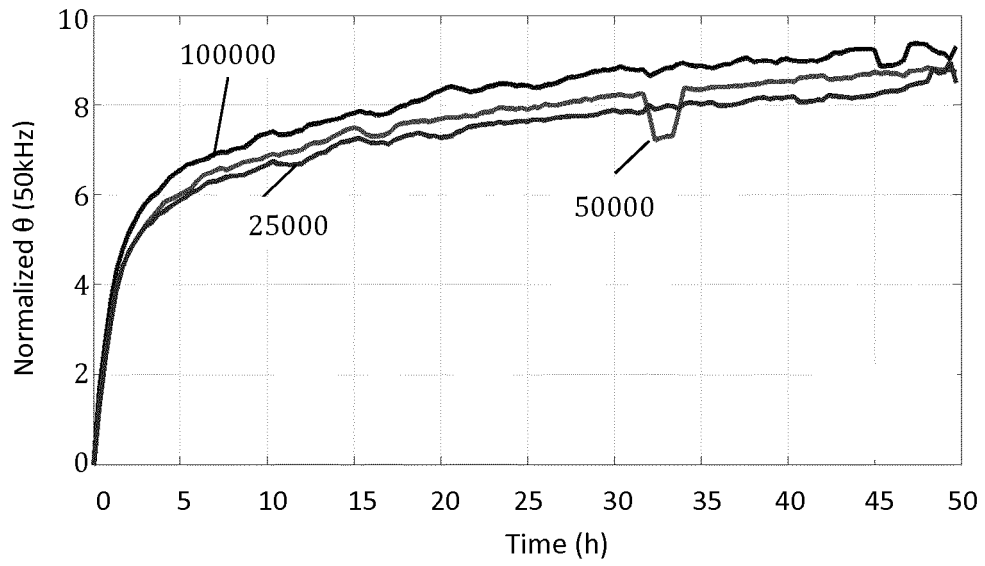
A cross-sectional view of a device assembly 800. The assembly includes a base layer 804 with a grid pattern. On top of the base layer is a layer 802, also with a grid pattern. A layer 805, with diagonal hatching, is positioned on top of layer 802. A layer 801, with a dotted pattern, is positioned on top of layer 805. A layer 806, with a vertical line pattern, is positioned on top of layer 801. A component 803, with diagonal hatching, is positioned on top of layer 805. A downward arrow is shown pointing to component 803.

FIG. 8

**FIG. 9****FIG. 10**

**FIG. 11****FIG. 12**

**FIG. 13****FIG. 14**

**FIG. 15**